

LINEAR TECHNOLOGY MATERIALS DECLARATION

ltc1702cgn#pbf

(Engineering Calculation)

SSOP

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TOTAL MASS (g) : 0.146447

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|---------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.004926 | 1000000 | 33636.8359375 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.058949 | 975000 | 402528.96875 | | |
| | | Iron (Fe) | 7439-89-6 | 0.001451 | 24000 | 9908.04882812 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000018 | 300 | 122.911705017 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000042 | 700 | 286.793945312 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.060460 | 1000000 | 412846.75 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.003400 | 1000000 | 23213.921875 | | |
| | | External Plating Total: | | | | 0.003400 | 1000000 | 23213.921875 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000484 | 1000000 | 3304.95874023 | | |
| Internal Plating Total: | | | | 0.000484 | 1000000 | 3304.95874023 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.001290 | 750000 | 8808.671875 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000430 | 250000 | 2936.22363281 | | |
| Die Attach Total: | | | | 0.001720 | 1000000 | 11744.8945312 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb Free | Resin (EP) | | 0.007726 | 103000 | 52756.4335938 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.067134 | 895000 | 458419.65625 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000150 | 2000 | 1024.26416016 | | |
| | | Encapsulation Total: | | | | 0.075010 | 1000000 | 512200.34375 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000447 | 1000000 | 3052.30712891 | | |
| | | | | | TOTAL MASS (g) : | 0.146447 | | |